

# **GBPC 12, 15, 25, 35 SERIES**

## **Bridege Rectifiers (Glass Passivated)**

## **Features**

- Integrally molded heatsink provided very low thermal resistance for maximum heat dissipation.
- Surge ovrload rartings from 300 amperes to 400 amperes.
- Isolated voltage from case to lead over 2500 volts.
- UL certified, UL #E96005

### Suffix "W"

Wire Lead Structure

## Suffix "M"

Terminal Location Face to Face







**GBPC-W** 



**GBPC** 

## Absolute Maximum Ratings \* $T_a = 25$ °C unless otherwise noted

Symbol	Parameter		Value						l lmita
			01	02	04	06	08	10	Units
V <sub>RRM</sub>	Maximum Repetitive Reverse Voltage		100	200	400	600	800	1000	V
V <sub>RMS</sub>	Maximum RMS Bridge Input Voltage		70	140	280	420	560	700	V
V <sub>R</sub>	DC Reverse Voltage (Rated V <sub>R</sub> )		100	200	400	600	800	1000	V
I <sub>F(AV)</sub>	Average Recitified Forward Current  @ T <sub>A</sub> = 55°C GBPC12 GBPC15 GBPC25 GBPC35				12 15 25 35				A A A
I <sub>FSM</sub>	Non-Repetitive Peak Forward Surge Current GBPC12, 25, 25 8.3ms Single Half-Sine-Wave GBPC35		300 400					A A	
T <sub>STG</sub>	Storage Temperature Range		-55 to +150					°C	
T <sub>J</sub>	Operating Junction Temperature		-55 to +150					°C	

<sup>\*</sup> These ratings are limiting values above which the serviceability of any semiconductor device may by impaired.

## **Thermal Characteristics**

Symbol	Parameter	Value	Units
$P_{D}$	Power Dissipation	83.3	W
$R_{\theta JL}$	Thermal Resistance, Junction to Lead	1.5	°C/W

## Electrical Characteristics T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parar	neter	Value	Units	
V <sub>F</sub>	Forward Voltage Drop, per b	ridge			
	@6.0A	GBPC12			
	@7.5A	GBPC15	1.1 (Max.)	V	
	@12.5A	GBPC25			
	@17.5A	GBPC35			
I <sub>R</sub>	Reverse Current, per elemer	nt			
	@ Rated V <sub>R</sub>	T <sub>A</sub> = 25°C	5.0 (Max.)	μΑ	
		T <sub>A</sub> = 125°C	500 (Max.)	μΑ	
	I <sup>2</sup> t Rating for Fusing				
	t < 8.35ms	GBPC12, 15, 25	375	A <sup>2</sup> Sec	
		GBPC35	660	A <sup>2</sup> Sec	
Ст	Total Capcitance, per leg				
-	$V_{R} = 4.0V$	GBPC12, 15, 25	180	pF	
	f = 1.0MHz	GBPC35	200	pF	

## **Typical Performance Characteristics**

Figure 1. Forward Current Derating Curve

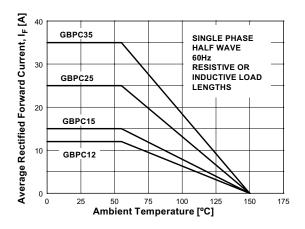
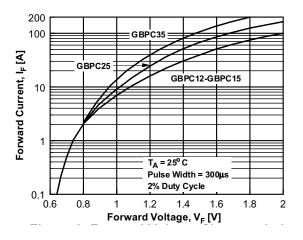


Figure 3. Forward Voltage Characteristics



**Figure 2. Non-Repetitive Surge Current** 

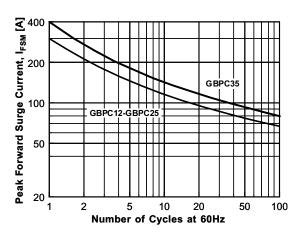
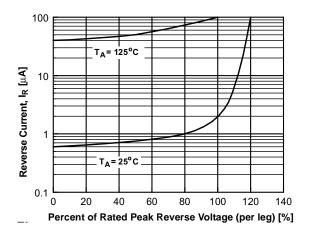


Figure 4. Reverse Current vs Reverse Voltage



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Across the board. Arour The Power Franchise <sup>®</sup> Programmable Active D		OPTOPLANAR™ PACMAN™ POP™	SILENT SWITCHER® SMART START™ SPM™	UniFET <sup>TM</sup> VCX <sup>TM</sup>

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Rev. I14